TEXAS INSTRUMENTS

Full-Featured –48-V Hot Swap Power Manager (TPS2392 and TPS2393)

User's Guide

DYNAMIC WARNINGS AND RESTRICTIONS

It is important to operate this EVM within the maximum input voltage ranges specified in Table 2.

Exceeding the specified input range may cause unexpected operation and/or irreversible damage to the EVM. If there are questions concerning the input range, please contact a TI field representative prior to connecting the input power.

Applying loads outside of the specified output range may result in unintended operation and/or possible permanent damage to the EVM. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative.

During normal operation, some circuit components may have case temperatures greater than 50°C. The EVM is designed to operate properly with certain components above 50°C as long as the input and output ranges are maintained. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors. These types of devices can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during operation, please be aware that these devices may be very warm to the touch.

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Full-Featured –48-V Hot Swap Power Manager (TPS2392 and TPS2393)

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ABSTRACT

The TPS2392 and TPS2393 integrated circuits are hot swap power managers optimized for use in nominal –48-V systems. They operate over a supply voltage range of –20 V to –80 V, and are rated to withstand spikes to –100 V. In conjunction with an external N-channel FET and sense resistor, they can be used to enable live insertion of plug-in cards and modules in powered systems. Each device provides load current slew rate control and peak magnitude limiting. Undervoltage and overvoltage shutdown thresholds are easily programmed via a three-resistor divider network.

Contents

1   Introduction

This User's Guide describes the use and features of the full-featured –48-V hot swap evaluation module (EVM). This EVM can be used to learn about the TPS2392 and TPS2393 hot swap power manager (HSPM) integrated circuits from Texas Instruments. The TPS2392 and TPS2393 are negative voltage hot swap controllers intended for use in systems needing to hot swap telecom distribution-level voltages. They integrate inrush current control, peak current limiting, electronic circuit breaker, enable input, powergood reporting, overvoltage and undervoltage protection, debounced insertion detection, and current fault indication. The EVM is a PCB-based tool featuring either device, and can be used to evaluate device operation in simulated live insertion events.

1.1   Features

The following list highlights some of the features of the TPS2392 and TPS2393 device.

- Wide input supply range of –20 V to –80 V

- Transient rating to –100 V

- Programmable current limit

- Programmable current slew rate

- Programmable UV/OV thresholds/hysteresis

- Debounced insertion detection inputs

- Open-drain power good (/PG) output

- Fault timer to eliminate nuisance trips

- Open-drain fault output ($\overline{\text{FAULT}}$)

- Enable input (EN)

- 14-pin TSSOP package

1.2   Description

The TPS2392 and TPS2393 integrated circuits are hot swap power managers optimized for use in nominal –48-V systems. They operate over a supply voltage range of –20 V to –80 V, and are rated to withstand spikes to –100 V. In conjunction with an external N-channel FET and sense resistor, they can be used to enable live insertion of plug-in cards and modules in powered systems. Each device provides load current slew rate control and peak magnitude limiting. Undervoltage and overvoltage shutdown thresholds are easily programmed via a three-resistor divider network. In addition, two active-low, debounced inputs provide plug-in insertion detection. A power good ($\overline{\text{PG}}$) output enables downstream converters. The TPS2392 and TPS2393 also provide the basic hot swap functions of electrical isolation of faulty cards, filtered protection against nuisance overcurrent trips, and single-line fault reporting.

The TPS2392 latches off in response to current faults. The TPS2393 periodically retries the load, to test for the continued existence of a fault.

2 The Full-Featured –48-V Hot Swap Controller EVM Kit

The full-featured –48-V hot swap controller EVM kit is a two-board platform that enables designers to rapidly learn about the TPS2392 and TPS2393 operation, and evaluate their performance during hot swap events. The main evaluation board (TI board number SLUP189–001 or SLUP189–002) is divided into two sections, one representing the backplane side of a typical telecom system, and the other containing the power interface section of a hot swap capable plug-in card. On the main EVM PCB, the two subsections are isolated. The EVM jumper card (TI board number SLUP190), when inserted into the main board's P1 connector, provides a mechanism for simulating hot swap events by abruptly applying power, ground and control signals on the backplane side to their corresponding inputs on the plug-in side.

2.1 The Full-Featured –48-V Hot Swap Controller EVM Main Board

2.1.1 Module Description

The full-featured –48-V hot swap controller EVM main board is divided into two separate circuits. When oriented such that the board nomenclature is upside right to the user, the left side of the board represents the backplane side of the hot swap interface; the right side represents the plug-in module side. This half contains the power isolation and control electronics comprising a hot swap interface that may be incorporated in a –48-V hot swap plug-in board. In addition, the right side of the main board contains some additional switches and components that can be used to facilitate device testing and for quick modifications of the plug-in characteristics. The two PCB sections connect to a 44-pin PCB edge connector (P1). Mate and demate of the plug-in is accomplished by inserting and removing the EVM jumper card.

The backplane side of the main board contains banana jacks for the connection of the –48-V power supply.

The plug-in side of the EVM board contains the TPS2392 or TPS2393 –48-V HSPM device, a power MOSFET switch, and some configuration capacitors. Two through-hole patterns are provided on the load side for the installation of large-value aluminum electrolytic capacitors. These capacitors simulate the input bulk capacitance that may be found on the target module's back-end supply plane. The EVM is supplied from the factory with a 100-μF capacitor installed in one of these locations. The second pattern, connected in parallel with the first, can be used to increase or otherwise modify the amount of load capacitance. With the TPS2392 and TPS2393, both inrush slew rate limiting and a fault time-out period are externally programmable using capacitors. On the EVM main board, several options are provided for slew rate limiting, for quick comparison of the effect of capacitor value on this function. The capacitors can be quickly switched in and out of the circuit via the DIP switch. Fault timing programming is set up in a similar manner; some amount of capacitance is hard-wired into the circuit, with the option of switching in additional capacitance.

The main board also contains some component patterns and connections to exercise the undervoltage (UVLO), overvoltage (OVLO), and insertion detection functions, and a switch to toggle the device enable input. Two possible circuits for interfacing the powergood output are also provided.

Test points are provided throughout the circuit for easy voltage monitoring via oscilloscope or voltmeter. The test point connections are listed in Table 6.

The pictorial of the full-featured –48-V hot swap EVM top assembly is shown in Figure 1.
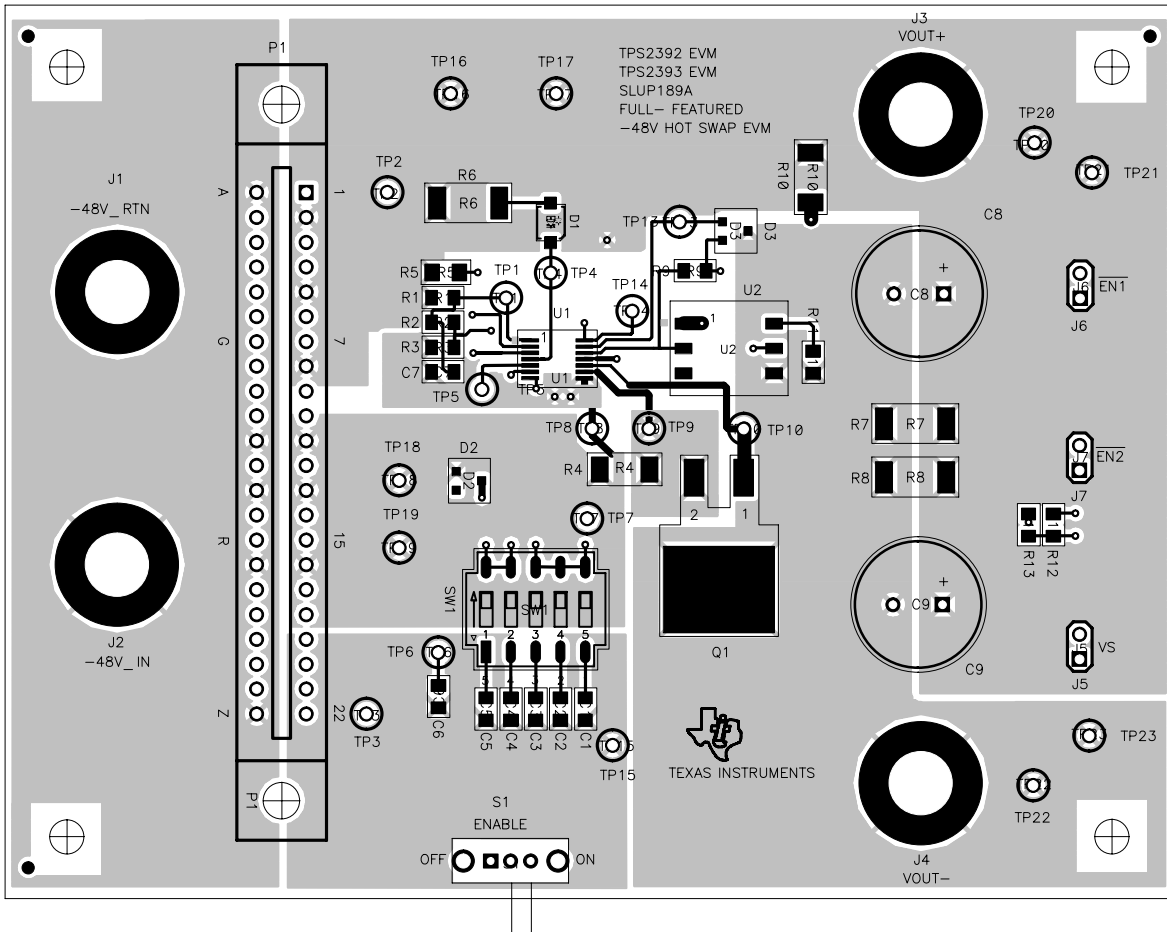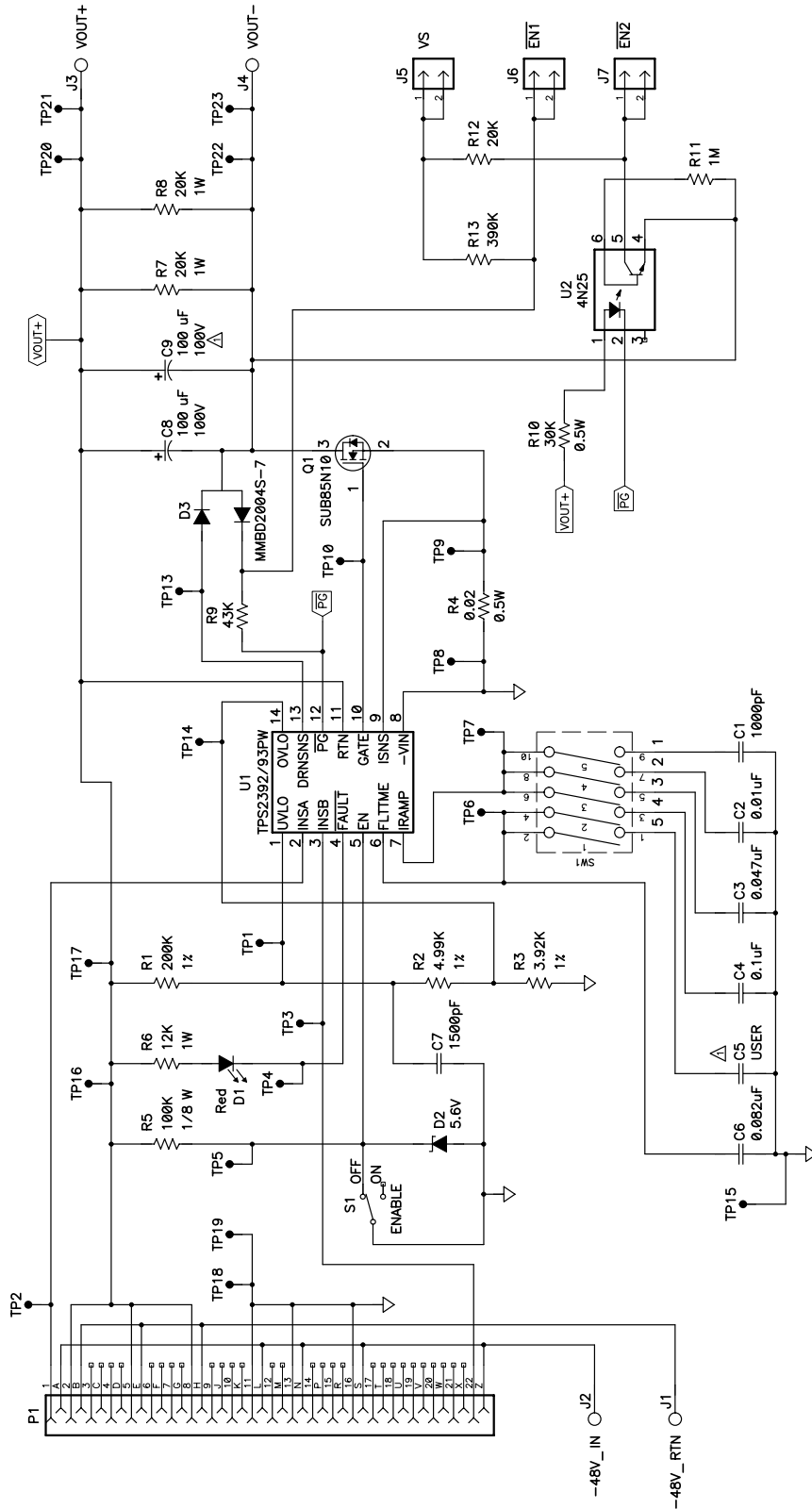
Figure 1. Evaluation Module Main Board Top Assembly

2.1.2   EVM Schematic Diagram and List of Materials

The EVM main board schematic diagram is shown in Figure 2. The EVM main board list of materials is provided in Table 1.

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Figure 2. –48-V Hot Swap Power Manager Evaluation Module Schematic

Table 1. Evaluation Module List of Materials

REF DES	QUANTITY		DESCRIPTION	MANUFACTURER	PART NUMBER
	–002	**–001**			
U1	1	–	IC, full-featured –48 V hot swap controller, w/retry	Texas Instruments	TPS2393PW
U1	–	1	IC, full-featured –48 V hot swap controller, latching	Texas Instruments	TPS2392PW
U2	1	1	IC, linear, optocoupler, 30 V, h(FE) = 0.2 min.	Fairchild	4N25.S
TP8, TP15, TP18, TP19	4	4	Jack, test point, black	Farnell	240–333
TP1–TP7, TP9, TP10, TP13, TP14, TP16, TP17, TP20 – TP23	17	17	Jack, test point, red	Farnell	240–345
S1	1	1	Switch, slide, SPDT, right angle, 200 mA	E–Switch	EG1213
SW1	1	1	Switch, dip, 5 position, SPST	CTS	219–05MS
R7, R8	2	2	Resistor, 20 kΩ, 1 W, 5%	Vishay	CRCW2512–203J
R6	1	1	Resistor, 12 kΩ, 1 W, 5%	Vishay	CRCW2512–123J
R10	1	1	Resistor, 30 kΩ, 0.5 W, 5%	Vishay	CRCW2010–303J
R4	1	1	Resistor, 0.02 Ω, 0.5 W, 1%	Vishay–Dale	WSL–2010 .020<1%
R5	1	1	Resistor, 100 kΩ, .125 W, 5%	Vishay	CRCW1206–104J
R1	1	1	Resistor, 200 kΩ, 0.1 W, 1%	Vishay	CRCW0805–2003F
R2	1	1	Resistor, 4.99 kΩ, 0.1 W, 1%	Vishay	CRCW0805–4991F
R3	1	1	Resistor, 3.92 kΩ, 0.1 W, 1%	Vishay	CRCW0805–3921F
R11	1	1	Resistor, 1.0 M, 0.1 W, 5%	Vishay	CRCW0805–105J
R13	1	1	Resistor, 390 kΩ, 0.1 W, 5%	Vishay	CRCW0805–394J
R9	1	1	Resistor, 43 kΩ, 0.1 W, 5%	Vishay	CRCW0805–433J
R12	1	1	Resistor, 20 kΩ, 0.1 W, 5%	Vishay	CRCW0805–203J
Q1	1	1	MOSFET, N-channel, V(BR) > 100 V, R_{DSon} = 10.5 mΩ MAX	Vishay–Siliconix	SUB85N10–10
P1	1	1	Connector, 44 pin, PCB vertical, .100 cntrs	Tyco	530843–4
N/A	1	1	Plug, keying, connector, intercontact	Tyco	650025–2
J5 – J7	3	3	Header, 2 pin, single row, .10–C, .025sq., .230 head	Sullins	PTC36SAxN
J1 – J4	4	4	Jack, banana, non-insulated, PC mnt.	Pomona	3267
D2	1	1	Diode, zener, 5.6 V at 5 mA, 0.35 W	Vishay–Semi	BZX84C5V6
D3	1	1	Diode, dual, series, switching, 240 V, 0.35 W	Vishay–Semi	GSD2004S–E9
D1	1	1	Diode, LED, ultra bright red, GW type	Panasonic	LN1261CAL
C9	–	–	Capacitor, aluminum elec, 100 μF, 100 V, 20%	Panasonic	EEU–FC2A101
C8	1	1	Capacitor, aluminum elec, 100 μF, 100V, 20%	Panasonic	EEU–FC2A101
C7	1	1	Capacitor, ceramic, 1500 pF, 25 V, 20%, X7R	Vitramon	VJ0805Y152MXXA
C1	1	1	Capacitor, ceramic, 1000 pF, 25 V, 10%, X7R	Vitramon	VJ0805Y102KXXA
C5	–	–	Capacitor, ceramic, 0805	Standard	Standard
C4	1	1	Capacitor, ceramic, 0.1 μF, 16 V, 10%, X7R	Vitramon	VJ0805Y104KXJA
C6	1	1	Capacitor, ceramic, 0.082 μF, 16 V, 10%, X7R	Vitramon	VJ0805Y823KXJA
C3	1	1	Capacitor, ceramic, 0.047 μF, 16 V, 10%, X7R	Vitramon	VJ0805Y473KXJA
C2	1	1	Capacitor, ceramic, 0.01 μF, 16 V, 10%, X7R	Vitramon	VJ0805Y103KXJA
N/A	4	4	Spacer, nylon, hex, #6–32, 0.625"	Eagle	14HTSP020
N/A	4	4	Screw, nylon, round head, #6–32, 0.25"	Eagle	010632R025
N/A	1	1	PCB, FR–4, 2 layer, SMOBC, 4.71" x 3.60", 0.062"	Texas Instruments	SLUP189
N/A	1	1	PCB, FR–4, 2 layer, SMOBC, jumper card	Texas Instruments	SLUP190

2.2 The Full-Featured –48-V Hot Swap EVM Jumper Card

2.2.1 Description

The EVM jumper card is used to apply the –48-V supply voltage, present at the input banana jacks, to the supply input of the main board's plug-in side. Inserting and removing the jumper card into and out of the main board P1 connector simulates hot swap events. There are no components mounted on the jumper card; it simply makes the point-to-point connections to apply input power to the plug-in electronics. This mechanism allows the EVM main board, which may have several scope probes and meter leads connected to it during use, to remain stationary on the user's bench.

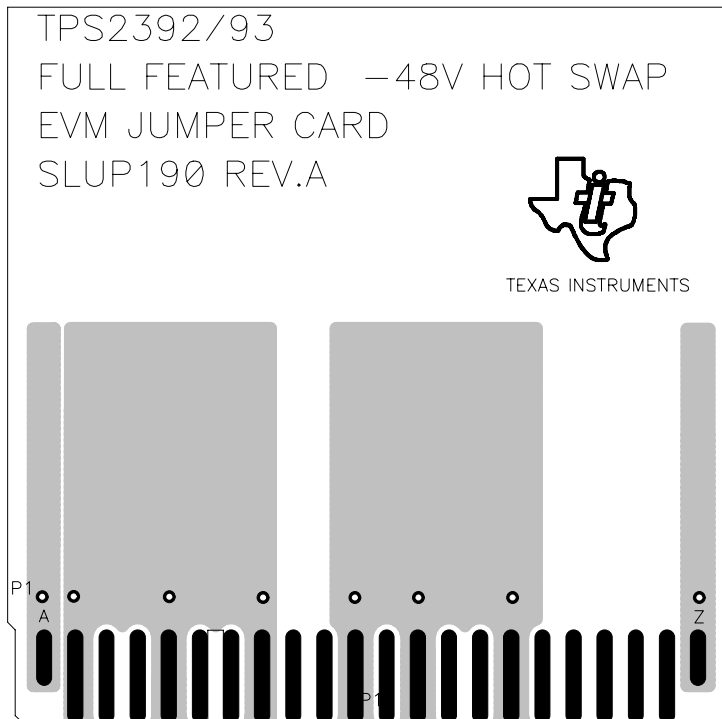A pictorial of the jumper card top layer is shown in Figure 3.

Figure 3. EVM Jumper Card Top Assembly

2.2.2   Jumper Card Schematic Diagram

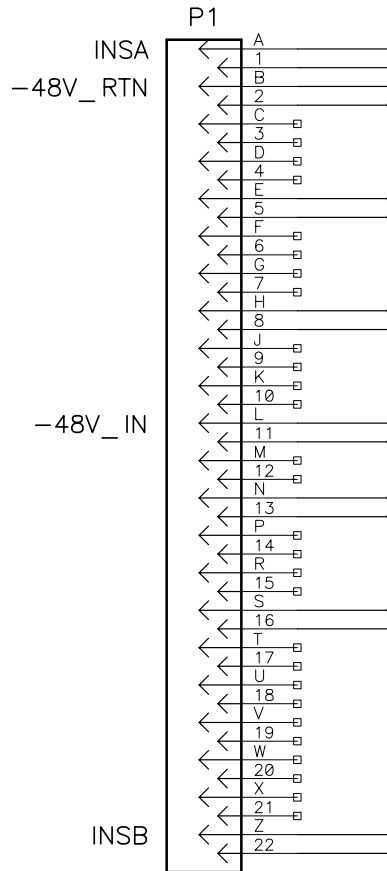The EVM jumper card schematic diagram is shown in Figure 4.

Figure 4. EVM Jumper Card Schematic

There are no components installed on the jumper card, and consequently no list of materials required.

2.3   Full-Featured –48-V Hot Swap EVM Operating Specifications

The full-featured –48-V hot swap EVM is intended to allow some degree of user reconfiguration. This allows designers to set up the circuit to better represent the characteristics of their target application. Potential modifications include changing the inrush limiting, the fault timing, and load characteristics. However, under no circumstances should the EVM kit be operated beyond the absolute maximum conditions specified in Table 2.

Table 2. EVM Absolute Maximum Ratings[1],[2]

PARAMETER	MIN	MAX	UNITS
Input voltage range, J1	–0.3	100	V
Input voltage range, J5 (Jumper Card installed)		100	V
Input voltage range, J5[3]		30	V
Load current, J3		–5	A
Load return current, J4		5	A
Ambient Operating Temperature Range	–40	85	°C

NOTES: (1)   Unless otherwise specified, voltages are with respect to the PCB –48V_IN node at J2.
(2)   Currents are positive into and negative out of the specified terminal.
(3)   Relative to the VOUT– node at J4.

As supplied from the factory, the –48-V hot swap EVM is configured for operation under the following target conditions, shown in Table 3.

Table 3. EVM Recommended Operating Conditions[1],[2]

PARAMETER	MIN	NOM	MAX	UNITS
Input supply voltage, J1	0	48	80	V
Input supply voltage, J5[3]	–1	5	20	V
Nominal load current, J3		–1		A
Nominal load return Current, J4		1		A
Operating temperature range	–40		85	°C

NOTES: (1)   Unless otherwise specified, voltages are with respect to the PCB –48V_IN node at J2.
(2)   Currents are positive into and negative out of the specified terminal.
(3)   Relative to the VOUT– node at J4.

3   Getting Started

3.1   Equipment Requirements

The following test equipment is required to use the full-featured –48-V hot swap EVM .

- Power supply, 80 VDC at 3 amps minimum
- Oscilloscope
- Digital voltmeter (DVM)

3.2   Verifying the EVM Operation

The following procedure steps may be used to verify functional operation of the EVM after receipt.

3.2.1   Equipment Setup

On the EVM board, place the ENABLE switch S1 in the OFF position.

Set the DIP switches 1 through 4 of switch SW1 to the ON position.

Turn on power supply number 1 and adjust the output for about 48 V. Verify the supply current limit is set to allow at least 3 amps. Turn on power supply number 2 and adjust its output to 5 V. Turn off the power supplies.

Connect the EVM and test equipment as shown in Figure 5.
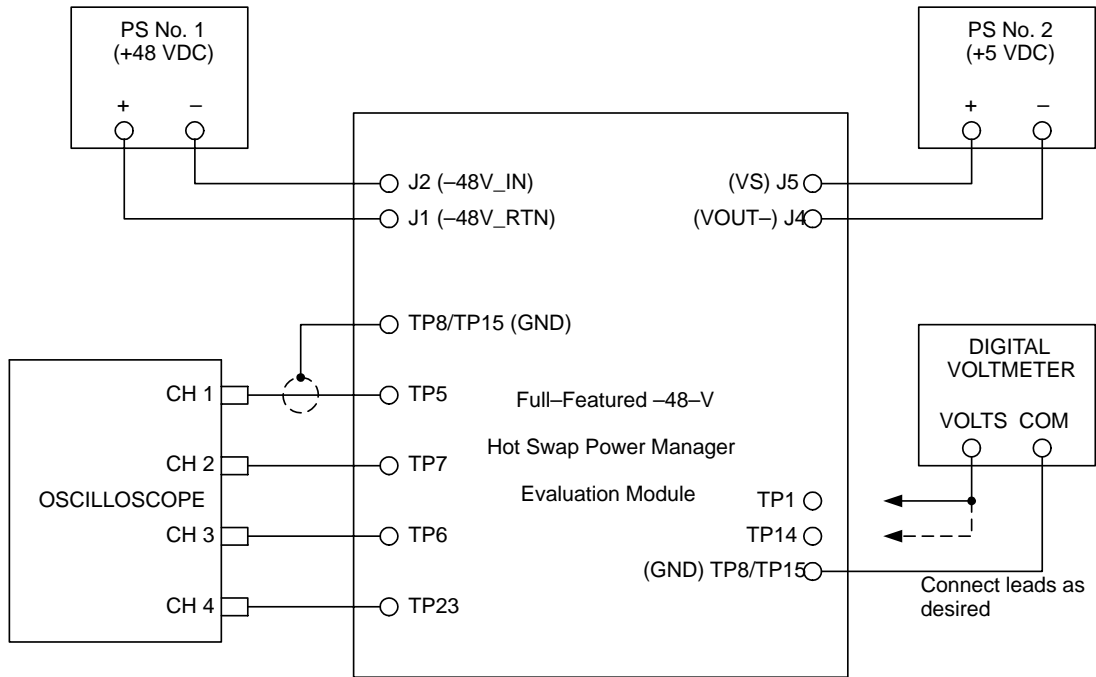

Figure 5. Full-Featured –48-V Hot Swap EVM Setup

On the oscilloscope, set the channel amplifiers to the following scales:

- CH1: 5 V/div
- CH2: 2 V/div
- CH3: 5 V/div
- CH4: 20 V/div

Set the scope to trigger on the rising edge of Channel 1, at about a 2.5-V level. Set the scope timebase to 10 ms, and the trigger mode to NORMAL.

3.2.2   Functional Test

Turn on both power supplies.

Insert the jumper card into the P1 connector, observing the proper insertion keying. On the EVM main board, verify the red LED (D1) is OFF. Verify the voltage readings indicated in Table 4 are obtained at the corresponding test points.

Table 4. Test Point Voltages (Outputs OFF)

TEST POINT	REFERENCE	VOLTAGE READING
TP1	TP8/TP15	Approx. 2.13 V
TP14	TP8/TP15	Approx. 0.94 V
TP20	TP22/J4	0 ± 200 mV
J6	TP22/J4	4.70 V min.
J7	TP22/J4	4.93 V min.

Place the ENABLE switch in the ON position. Verify the red LED (D1) remains off. The scope should have acquired a sweep similar to that shown in Figure 6.

EN (5 V/div.)
IRAMP (2 V/div.)

FLTTIME (5 V/div.)

VOUT – (20 V/div.)

t – Time – 10 ms/div.
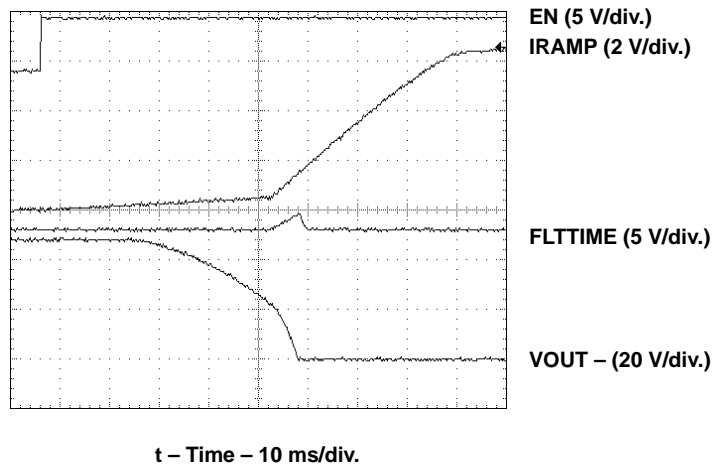
Figure 6. Load Ramp-Up Waveforms

The brief fault timing ramp which is shown in Figure 6 may or may not be present, depending on the actual values of the timing parameters for the particular board being used. If the load voltage ramps to full input potential during the initial reduced rate ramp period, then fault timing does not initiate.

The DMM can be used to verify that the voltages shown in Table 5 are present at the test points indicated.

Table 5. Test Point Voltages — Outputs ON

TEST POINT	REFERENCE	VOLTAGE READING
TP20	TP22/J4	~ Input Supply Voltage
J6	TP22/J4	< 0.8 V
J7	TP22/J4	250 mV MAX

Either place the ENABLE switch in the OFF position, or remove the jumper card, to remove power from the VOUT terminals.

4 Using the EVM Kit to Evaluate the TPS2392 and TPS2393

Procedures similar to the steps of Section 3.2.2 for functional test of the EVM can also be used to continue evaluation of the TPS2392 and TPS2393 hot swap controller devices. Additional details about the EVM features are provided in this section.

4.1 Supply Connections and Test Points

Supply connections to the EVM should be made as shown in Figure 5. The backplane, 48-V supply (power supply number 1 in Figure 5) connects to J1 and J2. The polarity of the circuit is such that the HI or (+) output of the supply connects to J1, –48V_RTN. The LO or (–) jack connects to J2, –48V_IN. PCB header J5 (VS) is used to connect an external pull-up source when using the $\overline{EN1}$ and $\overline{EN2}$ outputs of the module. This supply is referenced to the VOUT– node.

The full-featured –48-V hot swap EVM contains numerous test points located throughout the circuit for waveform monitoring. A list of the EVM test points and their associated signals is given in Table 6.

Table 6. Full-Featured –48-V Hot Swap EVM Test Points

TEST POINT	SIGNAL NAME	DESCRIPTION
TP1	UVLO	Sense input for supply undervoltage detection.
TP2	INSA	Insertion detection input A.
TP3	INSB	Insertion detection input B.
TP4	$\overline{FAULT}$	Load fault output of the TPS2392/93. On the EVM, this signal drives the red LED.
TP5	EN	Device enable input to turn on/off power to the load.
TP6	FLTTIME	Fault timing waveform of the TPS2392/93.
TP7	IRAMP	Current ramp control output waveform.
TP8	–VIN	Negative supply input and reference pin for the TPS2392/93. On the EVM, this is connected to –48V_IN when the Jumper Card is inserted.
TP9	ISENS	Current sense input of the controller.
TP10	GATE	Gate drive for pass FET Q1.
TP13	DRNSNS	Sense input of the controller for load voltage status.
TP14	OVLO	Sense input for supply overvoltage detection.
TP15	–VIN	Secondary test point on device reference node (located near timing capacitors).
TP16	VOUT+	Additional supply high side test points (located on input side of board, near TPS2392/93 power pin).
TP17		
TP18	–VIN	Secondary negative supply input test points. On the EVM, these are connected to –48V_IN when the Jumper Card is inserted.
TP19		
TP20	VOUT+	High side of switched (load) output power.
TP21		
TP22	VOUT–	Low side of switched (load) output power.
TP23		

4.2   Load Capacitors

Capacitor patterns C8 and C9 are available on the EVM for installation of components to represent the module input bulk capacitance; i.e., the load capacitance seen by the hot swap interface circuit. As supplied from the factory, the EVM contains a 100-µF aluminum electrolytic installed at C8. Further customization to approximate the user's application can be done using either C8 or C9. When installing capacitors in these mounting locations, care should be taken to observe the polarity marking on the PCB silkscreen, and to use appropriately rated capacitors for voltage withstanding. Generally, telecom applications should use 100-V minimum rated capacitors.

Banana jacks J3 and J4 are also connected across the output terminals, in parallel with C8 and C9. These jacks can be used to connect additional loads to the EVM board.

4.3   Changing the Current Limit Threshold

During power-up of a plug-in card, the TPS2392 and TPS2393 limit the peak inrush current drawn by the discharged bulk capacitance. The LCA senses load current as the drop across an external sense resistor. Current is regulated by slewing the gate of the pass FET to maintain the voltage drop at an internally set level, nominally 40 mV. Therefore, the peak current level can be established by selecting the appropriate sense resistor value. On the –48-V Hot Swap EVM, this resistor is R4. The default value of R4 is 20 mΩ. To modify the current limit threshold, a new sense resistor value can be determined from Equation 1.

$$R4 \leq \frac{VMAX}{IMAX}$$

(1)

where:

- VMAX is the sense voltage limit, and
- IMAX is the desired current limit threshold.

Using the device minimum value of 33 mV for VMAX along with the required minimum load current ensures that minimum amount of current can always be supplied to the load. For example, a particular line card is expected to draw a maximum of 1.2 A, when the power bus is at its operating minimum level of –33 V, once the card is powered up and operating normally. For this load characteristic, a sense resistor value less than 33 mV/1.2 A, or 27 mΩ, would be selected. A 25-mΩ resistor is generally the closest standard value readily available; smaller values also work, but with a corresponding increase in the maximum current limit.

4.4 Changing the Inrush Slew Rate

The TPS2392 and TPS2393 also feature slew rate limiting as current is ramped to charge the load capacitance. The slew rate is easily programmed, once the sense resistor is determined, with a small-value capacitor connected between the IRAMP and –VIN pins. The EVM comes equipped with three preset capacitor values, selectable either individually or combined by closing the appropriate DIP switches of SW1. The default values of the capacitors, and the corresponding nominal slew rates, are given in Table 7.

Table 7. –48-V Hot Swap EVM Default Slew Rates

SW1 DIP	REF DES	INSTALLED VALUE	SLEW RATE (A/S)
1	C1	1000 pF	5000
2	C2	0.01 µF	500
3	C3	0.047 µF	106

The EVM can be used to get an illustration of the relationship between current limit, inrush slew rate, load values, and the circuit's fault timing requirements. With DIP switch SW1–1 only closed, the fastest of the preset slew rates is selected, and only the hard-wired timing capacitor C6 is connected to the TPS2392 or TPS2393 controller. However, this is sufficient to allow the bulk capacitor C8 to fully charge, from 0 volts, across the full range of input supply voltages, down to –80 V. This can be observed by connecting input power as shown in Figure 5, displaying the VOUT– node on an oscilloscope, and enabling the device.

To observe the controller response to a load that does not charge up as expected (a shorted or otherwise excessive load), set switches SW1–1, SW1–2, and SW1–3 to the ON position. This greatly reduces the inrush (load charging) current slew rate at turn-on, with a corresponding increase in the amount of time needed to successfully charge the intended load. Increase the supply level to about 60 V to 80 V, and again enable the device. In this case, the voltage ramp time is excessively long relative to the programmed fault timer; the controller times out and turns off the load (See Note below). This can be seen from the illumination of the red LED. (For the TPS2393, the LED may flash briefly then turn off, indicating capacitor charging ultimately completed on a successive retry.) If this combination represented the parameters of the target plug-in module, then the timing capacitance of C6 and C4 (SW1–4 closed) would be more appropriate. The intended load, in this case, the 100-µF capacitor, can again be charged up over the input voltage range.

> **NOTE:** Due to tolerances of various EVM parameters, some units may not fault out under these conditions. Generally, this is due to the fact that the amount of voltage ramping during the reduced–rate turn–on period varies from device to device. Some units may be able to charge the load almost completely during this period, when fault timing is inhibited. A more severe load fault is needed to view the fault response. Additional capacitance, or even a resistor, can be connected across the VOUT terminals, J3(+) and J4(–) or at C9. If the user is confident the module is operating correctly, the load can also be shorted out to do this.

The inrush slew rate can be changed, to better match the application requirement, by replacing any capacitor C1, C2 or C3. The PCB patterns are sized for 0805 ceramic chip capacitors. Use equation 2 to calculate the new ramp capacitor, C_{RAMP}, value in microfarads.

$$C_{RAMP} = \frac{11}{100 \times R4 \times \left(\frac{di}{dt}\right)_{MAX}}$$

(2)

where:

- R4 is the selected sense resistor value, in ohms, and
- $(di/dt)_{MAX}$ is the desired maximum slew rate, in amps/second.

4.5 Fault Timing With the TPS2392/93

Whenever the hot swap controller is limiting current to the load, an on-chip timer is monitoring this operation against an established time limit. The timeout period is generated by the constant-current charging of a capacitor at the FLTTIME pin. If current regulation ceases prior to expiration of the timer, the capacitor is discharged, and normal steady-state operation of the load either starts or resumes. However, if the timer expires, then the pass FET is turned off, disabling power to the load, and the $\overline{\text{FAULT}}$ output is asserted.

On the EVM, several capacitor patterns are provided for adding or otherwise modifying the timeout period. Capacitor C6 is hard-wired to the device FLTTIME pin, and provides a minimum fault timer for the default load. C4 and C5 can be switched into the circuit via DIP switches SW1–4 and SW1–5, respectively. The EVM ships from the factory with a 0.1-µF capacitor installed at C4; C5 is not populated for easier subsequent user modification as required.

If the target application requires fault timing other than provided by the default EVM setup, a new value of timing capacitor can be calculated from Equation 3. When selecting from the readily available capacitor values for the Equation 3 result, default to a slightly larger, rather than smaller, capacitor.

$$C_{FLT} = \frac{55 \times t_{FLT}}{3.75}$$

(3)

where:

- C_{FLT} is the calculated value in microfarads, and
- t_{FLT} is the desired timeout period in seconds

4.6 Programming the UVLO and OVLO Thresholds and Hysteresis

The UVLO and OVLO pins can be used to set the circuit undervoltage and overvoltage thresholds (V_{UV} and V_{OV}, respectively). When the input supply is below V_{UV} or above V_{OV}, the GATE pin is held low, disconnecting power from the load, and the $\overline{\text{PG}}$ output is deasserted. When input voltage is within the UV/OV window, the GATE drive is enabled, assuming all other input conditions are valid for turn-on.

Threshold hysteresis is also externally programmable. Internal current sources are switched to the UVLO and OVLO pins whenever the corresponding input voltage exceeds the nominal 1.4-V reference. Please refer to the TPS2392/93 data sheet (TI Literature Number SLUS536) for additional details about the UVLO and OVLO comparator operation.

On the –48-V hot swap EVM, the V_{UV} and V_{OV} thresholds are individually programmed via the three-resistor divider R1, R2, and R3 (refer to Figure 2). The factory-installed resistor values result in the following nominal voltage thresholds.

Table 8. Nominal UVLO and OVLO settings.

PARAMETER	DESCRIPTION	VALUE (V)
V_{UV_L}	UVLO threshold, supply low ($V_{IN} < V_{UV}$)	32.8
V_{UV_H}	UVLO threshold, supply high ($V_{IN} > V_{UV}$)	30.8
V_{OV_L}	OVLO threshold, supply low ($V_{IN} < V_{OV}$)	72.6
V_{OV_H}	OVLO threshold, supply high ($V_{IN} > V_{OV}$)	70.5

The thresholds are easily modified by changing the resistor values. When the desired trip voltages and the UV hysteresis have been established for the protected load, new values are determined as follows. Generally, the process is simplest by first selecting the top leg of the divider (R1) needed to obtain the desired hysteresis. This value is calculated from Equation 4.

$$R1 = \frac{V_{HYS\_UV}}{10 \ \mu A} \tag{4}$$

where V_{HYS_UV} is the amount of undervoltage hysteresis.

Once a value for R1 is selected, it is used to calculate R2 and R3 using Equations 5 and 6.

$$R2 = \frac{1.4 \times R1}{\left(V_{UV\_L} - 1.4\right)} \times \left[1 - \frac{V_{UV\_L}}{\left(V_{OV\_L} + 10^{-5} \times R1\right)}\right] \tag{5}$$

$$R3 = \frac{1.4 \times R1}{\left(V_{UV\_L} - 1.4\right)} \times \left[\frac{V_{UV\_L}}{\left(V_{OV\_L} + 10^{-5} \times R1\right)}\right] \tag{6}$$

where:

- V_{UV_L} is the UVLO threshold when the input supply is low; i.e., less than V_{UV}, and

- V_{OV_L} is the OVLO threshold when the input supply is low; i.e., less than V_{OV}

4.7 TPS2392/93 Powergood Output ($\overline{PG}$)

The –48-V hot swap EVM contains two possible circuits for interfacing to the device $\overline{PG}$ output pin. The outputs of these circuits are available at the PCB headers J6 and J7 as the $\overline{EN1}$ and $\overline{EN2}$ signals, respectively. An example application of these signals is to drive the enable input of downstream converters. As such, both outputs are referenced to the VOUT– node of the EVM, as this would be the low side of input power to the brick.

The $\overline{EN1}$ output is generated via the resistive translation of the device $\overline{PG}$ output. The EVM schematic of Figure 2 shows the circuit details. This active-low output is capable of sinking a minimum of 10 μA at a maximum output voltage of 0.8 V(TTL–compatible V_{OL}), across the complete range of the 48-V input supply and ambient operating temperature. (The default UVLO and OVLO thresholds are assumed.)

The $\overline{EN2}$ output demonstrates an isolated signal implementation using an opto device. The EVM schematic shows the circuit details. This active-low output is capable of sinking a minimum of 150 μA across the complete range of input supply voltage and ambient operating temperature.

The use of these enable signals requires a pull-up source at the VS input, J5. See Tables 2 and 3 for the requirements of the VS supply.

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